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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application: Takahiro IJIMA et al. ]

Serial No.: 09/736,864 ]

Filed: December 14, 2000 ]

For: INTERCONNECTION SUBSTRATE ]  
HAVING METAL COLUMNS COVERED BY A ]  
RESIN FILM AND MANUFACTURING ]  
METHOD THEREOF ]

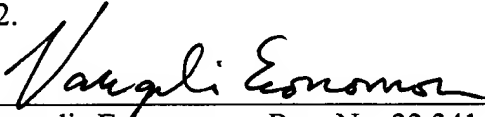
GRP ART UNIT : 2815

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**Certification under 37 C.F.R. §1.8(a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on August 20, 2002.

  
Vangelis Economou – Reg. No. 32,341

Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT UNDER 37 C.F.R. §1.111**

Sir:

In response to the Office Action dated June 25, 2002, please amend the above-captioned application as follows:

**IN THE CLAIMS:**

Please substitute the following claims 1, 11 and 13 in clean copy format for the pending claims 1, 11 and 13. A marked up copy of the claims is attached to indicate the amendments.